

Reverse Costing® CATALOGUE

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MEMS

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REVERSE COSTING®

A complete set of information to understand the technology and cost of the electronic devices on the market. System Plus Consulting Reverse Costing® reports are based on in-house developed methodology and costing tools which ensure their single format. The full collection is regularly updated on our website. These reports can be ordered individually or under our Annual Subscription.

IMAGING

Ref.	Date Pages	Manufacturer Product	Type of Product	Overview
VISIBLE				
SP18387	2018/3 100	ams Apple iPhone 8	Color Sensor in the Apple iPhone 8	Full analysis of the package and sensor die, cost analysis and price estimate for the device. Comparison with the ams TCS3400.
SP18385	2018/5 102	ams AS726X Series	Color Sensor	Full analysis from sensor die to packaging along with a cost analysis and a price estimate for the device.
SP18355	2018/7 115	Hamamatsu C12880MA	C12880MA Micro-spectrometer	Detailed physical analysis with process description and manufacturing cost analysis
SP17377	2017/12 99	ams Apple iPhone X	Multi-Spectral Sensor	Analysis of the complete multi-spectral ALS, from the sensor die to the custom packaging developed for the device. Complete cost analysis and a price estimate for the device
SP17348	2017/11 350	Various	Camera Module	Explanation of the main players' technology choices and comparison between competitors.
SP17343	2017/7 130	Sony IMX400	22MPix tri-layer stacked CIS	The first tri-layer stacked CIS on the market includes a 22 Mpixel array, a 1Gb DRAM die and a digital signal processor (DSP) on the same die footprint.
SP17338	2017/8 122	Samsung Galaxy S8	Iris Scanner	Description of the supply chain of the full system including the IR camera module, CIS and infrared LED. Comparison with the Fujitsu iris.
SP17334	2017/6 94	NanoLambda NSP32-V1	Nano Spectrometer	First plasmonic filter sensor for consumer devices could disrupt optical applications
SP17326	2017/3 113	STMicroelectronics iPhone7	Time of Flight Proximity Sensor	A look inside Single Photon Avalanche Diode (SPAD) Technology from STMicroelectronics entering the High-End Apple Handset
SP17304	2017/3 165	Consumer Physics Scio	Spectrometer	World's first pocket size Molecular sensor that can be integrated into consumer smartphones
SP16293	2016/11 145	Apple iPhone 7 Plus	Rear-Facing Dual Camera Module	In the iPhone 7 Plus, Apple introduced a dual rear camera module. The module features two sensors, one with a totally new structure.
INFRARED				
SP18438	2018/12 160	Mantis Depth Sensing System	Xiaomi Mi8 Explorer	Analysis of the complete 3D depth sensing system, including a complete analysis of the NIR camera module, and the dot projector. cost analysis and price estimation for the system
SP18434	2018/11 170	Orbbec 3D Depth Sensing System	Oppo Find X	Complete analysis of the 3D depth sensing system, including a complete analysis of the NIR camera module, the dot projector and the SoC.
SP18405	2018/8 200	Samsung & Apple S8 and S9 and iPhone	ALS & Proximity Sensor	Analysis of the packaging and the sensor die along with a cost analysis calculation for all the devices.
SP18404	2018/5 90	Intel RealSense D435	3D Active IR Stereo Depth Camera	Complete teardown analysis of the RealSense D435, with high definition pictures of the vision processor, VCSEL IR projector and image sensor dies and the BOM.

IMAGING

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SP18396	2018/4 121	Heimann Sensor HTPA32x32d	32 x 32-array thermopile LWIR	Detailed teardown and cost analysis of the thermopile die, the silicon lens, the EEPROM die, and the packaging.
SP18383	2018/1 172	STMicroelectronics Apple iPhone X	TOF Proximity Sensor & Flood Illuminator	Complete analysis of the microsystem, from the two illumination devices (VCSEL) to the collector (based on the SPAD developed by STMicroelectronics).
SP17378	2017/12 97	STMicroelectronics Apple iPhone X	Camera Sensor	Analysis of the complete NIR camera sensor (module and the sensor die) and cost analysis and a price estimate of the device.
SP17376	2017/12 150	Apple iPhone X	Infrared Dot Projector	Description of the full system's technology and manufacturing process, including the package, VCSEL, electronics, the folded optic and the DOE.
SP17349	2017/9 170	FLIR Boson	Camera and 12µm microbolometer	Detailed teardown and cost analysis of the microbolometer, lens and WLP. Bill-of-material (BOM) of the camera core, and manufacturing cost of the infrared camera.
SP17337	2017/7 79	Texas Instrument	Time of Flight Image Sensor	A look into Texas Instruments' system-on-chip, including Sony/Softkinetic's time-of-flight pixel technology, for industrial applications
SP17336	2017/7 80	Melexis MLX75023	ToF imager	A cutting-edge ToF imager technology from Sony/Softkinetic, adapted by Melexis for automotive in-cabin applications
SP17330	2017/6 203	Autoliv ISC0901	Night Vision Automotive Camera	Autoliv's 3rd Generation Automotive Night Vision Camera with FLIR's ISC0901 Microbolometer
SP17305	2017/1 170	Lenovo	3D Time of Flight (ToF) Camera	World's first 3D tri-camera bundle including Infineon/pmd REAL3TM ToF image sensor integrated into a consumer smartphone
SP16264	2016/8 170	i3system Thermal Expert	IR camera and microbolometer	Based on a high definition microbolometer from I3system (I3BOL384_17A), the Thermal Expert infrared camera is a high-end product for smartphones.

INTEGRATED CIRCUITS

Ref.	Date Pages	Manufacturer Product	Type of Product	Overview
OTHER				
SP18427	2018/9 112	Various Bluetooth 5	System-on-Chip Comparison 2018	Complete cost analysis and a cost estimation of the SoCs. Exhaustive comparison between the studied samples.
SP17335	2017/8 146	Various Bipolar-CMOS-DMOS	BCD Technology & Cost review	Details on the manufacturing process and materials used, estimation of the cost structure highlighting the influence of the technological innovations.

MEMORY

Ref.	Date Pages	Manufacturer Product	Type of Product	Overview
3D NAND				
SP18422	2018/12 245	Various 3D NAND Memory	Leading-edge 3D NAND Memory Comparison	Detailed study of the latest NAND dies and die cross-section and processes. Detailed physical analysis, highlighting the cell design and memory storage type.

MEMS & SENSOR

Ref.	Date Pages	Manufacturer Product	Type of Product	Overview
PRINTHEADS				
SP18421	2018/9 150	Xaar 1201 GS2p5 PZT	Xaar 1201 GS2p5 PZT Printhead	Insight into technological data, manufacturing cost, and selling price of the MEMS inkjet manufactured by Ricoh and the 1201 printhead supplied by Xaar
SP18420	2018/9 158	Epson PrecisionCore	Printhead with MicroTFP Inkjet Dies	Insight into technological data, manufacturing cost, and selling price of the microTFP inkjet MEMS and the PrecisionCore printhead by Epson.
PRESSURE SENSOR				
SP18385	2018/5 160	Various MEMS Pressure Senso	MEMS Pressure Sensor Comparison 2018	Multiple comparisons based on physical analyses of 34 MEMS pressure sensor components

MEMS & SENSOR

Ref.	Date Pages	Manufacturer Product	Type of Product	Overview
SP17358	2017/11 108	Bosch BMP380	Digital Barometric Pressure Sensor	Deep technological and cost analyses of the BMP380. Technical and price comparison with the LPS22HB from STMicroelectronics and Bosch BME280 and BME680.
SP17308	2017/2 104	Infineon DPS310	Capacitive Pressure Sensor	Tiny MEMS digital barometer for smartphones and wearables
SP16295	2016/11 128	STMicroelectronics LPS22HB	Nano Pressure Sensor	The new pressure sensor from ST, is compared with the 1st-generation STMicroelectronics LPS331AP pressure sensor and the Bosch Sensortec BMP280
SP16279	2016/9 96	Melexis MLX91802	TPMS	The Melexis MLX91802 is an absolute pressure sensor used in tire pressure monitoring systems (TPMS) for cars and trucks.
MICROPHONE				
SP18384	2018/3 215	Various Apple iPhone X	iPhone X – MEMS Microphones	Complete teardown and comparison between each supplier.
SP17314	2017/2 109	Vesper VM1000	Piezoelectric Microphone	Disruptive first Piezoelectric MEMS microphone for consumer applications.
SP16296	2016/10 106	Goertek iPhone7 Microphone	MEMS Microphone iPhone 7	Goertek MEMS Microphone (Infineon solution) in Apple iPhone 7 Plus
SP16294	2016/10 106	STMicroelectronics iPhone7 Microphone	MEMS Microphone iPhone 7	STMicroelectronics MEMS Microphone in Apple iPhone 7 Plus
SP16292	2016/10 113	Knowles iPhone7 Microphone	MEMS Microphone iPhone 7	Knowles MEMS Microphone in Apple iPhone 7 Plus
MEDICAL				
SP17346	2017/7 130	Thermo Fisher Ion 520	Sequencing chip	Complete analysis of the Ion 520 chip from Thermo Fisher, featuring chip disassembly and die analyses, processes and cross-sections.
IMU/COMBO				
SP18382	2018/1 190	Bosch 6-Axis IMU	6-Axis IMU in the Apple iPhone X	Physical analysis, with process description and manufacturing cost analysis. Comparison with Bosch Sensortec's BMI160, InvenSense and STMicroelectronics' latest 6axis IMUs.
SP17361	2017/10 175	InvenSense ICM-20789	Pressure Sensor Combo	Detailed technology and cost analysis of the ICM-20789 7-axis motion tracking device. Comparison with the previous generation of combo sensors from InvenSense
SP16297	2016/12 155	STMicroelectronics LSM6DSM	6-axis IMU dedicated to OIS	Complete reports and comparison of the latest generation of inertial measurement units for consumer optical image stabilization applications
SP16291	2016/12 136	InvenSense iPhone 7 Plus	6-axis IMU	Complete reports and comparison of the latest generation of inertial measurement units for consumer optical image stabilization applications
GYROSCOPE				
SP18381	2018/1 141	Tronics Microsystems GYPRO3300	Angular Rate Sensor	Analysis of the complete component, including the package, MEMS, and ASIC dies description of the ASIC and MEMS functionalities.
SP16299	2016/11 87	Invensense IDG-2030	Gyroscope fo OIS	2-axis thin gyroscope for camera OIS
SP16298	2016/11 105	STMicroelectronics L2G2IS	Gyroscope fo OIS	2-axis thin gyroscope for camera OIS
FINGERPRINT				
SP18419	2018/7 125	Synaptics and Goodix VIVO X21	Synaptics' Under-Display Fingerprint Scanner <i>Inside the VIVO X21 UD</i>	Comparison with the latest Huawei FPC1268 fingerprint touch sensor and a physical comparison with the Goodix Version of Vivo's fingerprint scanner
SP17318	2017/4 115	Fingerprint Cards FPC1228	Capacitive under glass fingerprint sensor	Huawei P10 and Mate 9 pro capacitive fingerprint successfully integrated under glass in collaboration with TPK
ENVIRONMENT				
SP18398	2018/10 150	Various Miniaturized Gas Sensc	Miniaturized Gas Sensor	Comparison 2018 : Analysis of the packaging and the sensor die along with a cost analysis for all devices.

MEMS & SENSOR

Ref.	Date Pages	Manufacturer Product	Type of Product	Overview
SP18372	2018/2 125	Sensirion SGP30	SGP30 Gas Sensor	Analysis of the entire component, including the package, MEMS, and ASIC die. Full description of the ASIC and MEMS functionalities as well as manufacturing processes.
SP17342	2017/7 152	Bosch BME680	Environnement Sensor	The world's first environmental sensor combining gas, pressure, humidity and temperature sensing functions in a 3mm x 3mm footprint package.
COMPASS				
SP15222	2015/10 160	eCompass Review	3-Axis & 6-Axis	Over 20 eCompasses from the main players analyzed and compared !
ACCELEROMETER				
SP17315	2017/3 130	mCube MC3672	WLCSP MEMS Accelerometer	Ultra-low power - Highly integrated WLCSP Accelerometer with Via-Middle TSV
SP17269	2017/1 110	Safran Colibrys VS1000	High End Accelerometer	Single-Axis High Performance Accelerometer with new ASIC design

PACKAGING

Ref.	Date Pages	Manufacturer Product	Type of Product	Overview
OTHER				
SP18430	2018/11 160	Various Wafer	Wafer to Wafer Permanent Bonding	Analysis of each component's wafer bonding process, including component dimensions, cost and manufacturing approach.
EMBEDDED				
SP17306	2017/6 90	TDK SESUB-PAN-T2541	Embedded die bluetooth module	TDK SESUB-PAN-D14580 Module: world's smallest Bluetooth 4.1 low energy (LE)
3D PACKAGING				
SP18417	2018/10 160	Intel	EMIB	Complete physical analysis of the packaging process, with details of all technical choices regarding processes, equipment and materials.
SP18406	2018/6 130	Samsung, Qualcomm ios 9810, Snapdragon	Samsung's Galaxy S9 + Processor Packages	Review of the Exynos 9810 and the Snapdragon 845, including a complete package analysis, cost analysis, and price estimate for the chips.
SP18393	2018/7 157	Qualcomm WiGig Chips	Qualcomm WiGig Chipset Smartphone	Full investigation of the system, featuring a detailed study of the SiPs and the antenna board including die analyses, processes and board cross-sections
SP18374	2018/1 145	Qualcomm QCA9500	WiGig Chipset	Full investigation of the module, featuring a detailed study of the SiP and the antenna board including die analyses, processes and board cross-sections.
SP18373	2018/2 140	TSMC Apple A11 inFO PoP	inFO Packaging in iPhone X	Analysis of the packaging from the DRAM memory to the LSC developed by TSMC. Comprehensive cost analysis and price estimation of the device.
SP17360	2017/11 130	AMD eon Vega Frontier Edi	SPIL CoW last – Samsung HBM2	Complete physical analysis of the packaging process. Comparison with NVIDIA's Tesla P100 and AMD's Fury X.
SP17353	2017/10 130	TSMC, Samsung NVIDIA Tesla P100	GPU accelerator with HBM2	Complete physical analysis of the packaging process, description of the manufacturing supply chain and calculation of the manufacturing costs.
SP17352	2017/10 300	Various MEMS Packaging	Mems Packaging	Multiple comparisons based on physical analyses of over 100 MEMS components.
SP17339	2017/6 133	NXP SCM-i.MX6	Quad High Density Fan-Out Wafer-Level SiP	NXP SCM-i.MX6 Quad High Density Fan-Out Wafer-Level System-in-Package
SP16303	2016/12 100	Various	Application Processors Comparison	Comparison of main players AP: Apple A10 with inFO vs. Qualcomm Snapdragon 820 with MCeP packaging technology vs. HiSilicon Kirin 955 & Samsung Exynos8 with standard PoP
SP16290	2016/10 100	TSMC inFO	Package-on-Package	Deep Analysis and reverse costing of the new inFO packaging technology from TSMC used for the latest Apple's Application processor, the A10 found in the iPhone 7
SP16276	2016/6 113	Qualcomm Snapdragon 820	Package-on-Package	The Galaxy S7 integrates the Exynos 8 with classic PoP packaging or the Snapdragon 820, with Molded Core Embedded Package (MCeP) technology, developed by Shinko.

PASSIVE

Ref.	Date Pages	Manufacturer Product	Type of Product	Overview
OTHER				
SP17344	2017/9 140	Various Silicon Capacitor	Silicon Capacitor	Details on the manufacturing process and materials used, component design, and die size. Comparison of the components' sizes, materials and characteristics.
SP16300	2016/10 100	TSMC Silicon Capacitor	Deep Trench Capacitor	Deep analysis and Reverse Costing of the new silicon capacitor technology from TSMC used for the latest Apple's Application processor, the A10 found in the iPhone 7

POWER

Ref.	Date Pages	Manufacturer Product	Type of Product	Overview
SiC				
SP18428	2018/8 95	Rohm Gen3 Trench	Rohm SiC MOSFET Gen3 Trench Design Family	Analysis of the Gen3 trench MOSFETs at 650V and 1200V, with optical and scanning electron microscope (SEM) images of the complex SiC trench structure.
SP18413	2018/6 100	STMicroelectronics Tesla Model 3	Tesla Model 3 Inverter with SiC Power Module	Estimation of the production cost of the SiC MOSFET and package. Technical and cost comparison with the Mitsubishi J-Series TP-M power module.
SP18410	2018/6 74	UnitedSiC UJN1205K	1200V SiC JFET	Analysis of the UJN1205K device, assembled in a TO247 package as well as production cost analysis, and comparisons with its JFET counterpart from SemiSouth
SP18390	2018/4 55	Littelfuse LSIC1MO120E0080	SiC MOSFET	Complete BoM, die manufacturing, and packaging processes. Estimated manufacturing cost, a comparison with similar products from STMicroelectronics and CREE.
SP18366	2018/2 140	Infineon JF11MR12W1M1_B11	1200V CoolSiC MOSFET Module	Full teardown of the module's components and housing.
SP17310	2017/4 65	Rohm SCT2H12NZGC11	1700V SiC MOSFET	In its new series of SiC MOSFETs, Rohm uses trench structures for 650V and 1200V products, while 1700V products use planar structures
SP17309	2017/1 66	STMicroelectronics STC30N120	1200V SiC MOSFET	The 1st generation 1200V SiC MOSFET device from STMicroelectronics has good current density at a very competitive cost
OTHER				
SP18399	2018/7 110	Various	Automotive Power Module Packaging	Comparison 2018 of the structures and costs of the different technological choices made by key manufacturers of the automotive industry
SP18359	2018/5 115	Various	Power Discrete Packaging	Comparison 2018 : Summary of the state of the art of packaging power semiconductors at a discrete level. Comparison of 20 types of packages.
MOSFET				
SP18380	2018/1 75	Wolfspeed C2M0025120D	1200V SiC MOSFET	Deep technology analysis of the package and components, with images of the planar SiC structure. Comparisons with Rohm and ST SiC MOSFETs and 1200V silicon IGBTs.
SP17350	2017/8 335	Various 100V MOSFET	100V MOSFET Comparison	Details on the manufacturing processes and materials used, packaging structures, component designs, die sizes, electrical performance and current densities, and cost structure
SP17333	2017/6 70	ON Semiconductor FDMS86181	100V 124A Trench MOSFET	The newest technical innovations in the device and package made by ON Semiconductor/Fairchild
SP16289	2016/11 171	Various	40V Silicon MOSFET	Technology and Cost Review of 40V Si MOSFET
IGBT				
SP18408	2018/10 185	Mitsubishi J1- Series 650V	Mitsubishi J1- Series 650V	Technology and cost analysis of two J1-series power modules with 650V and 600A/1000A: the CT600CJ1A060 and the CT1000CJ1B060
SP18388	2018/9 225	Various 1200V	1200V Silicon IGBT vs SiC MOSFET	Comparison 2018 with design information, estimated production cost for every transistor and comparison of the different components available on the market
SP18375	2018/1 115	Infineon FF400R07A01E3	Double Side Cooled IGBT Module	Estimation of the production cost of the IGBT, diode and package and technical and cost comparison between Infineon's design and the Toyota Prius inverter's DSC power module
SP17332	2017/6 87	Infineon FS820R08A6P2B	750V IGBT Module	The HybridPACK™ Drive is a very compact power module optimized for hybrid and electric vehicle.

POWER

Ref.	Date Pages	Manufacturer Product	Type of Product	Overview
SP16288	2016/12 195	Various	IGBT vs SiC MOSFET comparison	1200V SiC MOSFET vs Silicon IGBT: Technology and cost comparison
GaN				
SP18411	2018/10 110	Qorvo QPF4006 39GHz	Qorvo QPF4006 39GHz GaN MMIC	Detailed analysis of the packaging and the GaN on SiC transistor with optical SEM Pictures as well as a cost analysis.
SP18391	2018/6 97	GaN Systems GS61004B	100V GaN HEMT	Estimated production cost for the epitaxy and the package. Comparison of the standard 100V Si MOSFETs and low-voltage GaN on Si HEMT.
SP18365	2018/4 200	Various	GaN-on-Silicon Transistor Comparison	Estimated production cost for the integrated circuit gate driver, transistor, and package. Comparison of the different components available on the market.
SP18363	2018/2 100	Texas Instruments LMG5200	80V GaN FET Power Stage	Estimated production cost for the IC gate driver, FET, and package. Comparison with the packaging and epitaxy from GaN Systems, Transphorm, and Panasonic.
SP17362	2017/9 82	EPC EPC2045	100V GaN-on-silicon Transistor	Estimation of the production cost of the epitaxy and the package, comparison with previous EPC devices and epitaxy.
SP17331	2017/7 104	Texas Instruments LMG3410	600V GaN-on-Silicon HEMT	The LMG3410 Single-Channel Gallium-Nitride (GaN) Power Stage contains a 70-mΩ, 600-V GaN power transistor and specialized driver in an 8-mm by 8-mm QFN package.
SP17322	2017/5 72	Panasonic PGA26E19BA	600V GaN-on-Silicon HEMT	Panasonic abandons the TO220 package for its GaN HEMTs and proposes the DFN 8x8 package for the latest 600V device.
SP17319	2017/5 98	Transphorm TPH3208PS	650V GaN HEMT	A new 650V GaN HEMT from Transphorm with a simplified cascode structure and enhanced electrical characteristics.
SP17311	2017/2 78	Panasonic PGA26C09	600V GaN-on-Silicon HEMT	The first 600V GaN HEMT of Panasonic is designed with an innovative structure to integrate a normally Off transistor in a standard package without cascode.
SP16302	2016/11 120	Transphorm TPH3206PS	GaN-on-Silicon HEMT	Transphorm's TPH3206PS transistor has a new die design and manufacturing process. The die contacts are optimized on the die area to save space, and increase current density.
SP16286	2016/10 66	Wolfspeed CGHV40100F	GaN-on-SiC HEMT	The CGHV40100 includes a single GaN-on-SiC HEMT die for RF applications. The device is assembled in a SOT467C package;

RF

Ref.	Date Pages	Manufacturer Product	Type of Product	Overview
RF MODULE				
SP18389	2018/4 600	Various	RF Front-End Modules Comparison 2018	Description of each component and statistical analyses for most front-end modules.
SP18379	2018/2 160	Broadcom AFEM-8072	Mid&High Band LTE FEM	Analysis of the full FEM SiP, including the RF IC and its IPDs, the filtering dies and the internal and external EMI shielding.
SP18368	2018/10 397	Various	Automotive Radar	Comparison 2018 : Description of each component and statistical analyses for most radar systems focusing on the RF board.
SP17364	2017/11 140	Various	RF SiPs	Description of each component and important data, including type of substrate, proportion of silicon in the module and line spacing.
RF IC				
SP18418	2018/8 150	Peraso X710	Peraso X710 Chipset 60GHz	Full investigation of the system, with a detailed study of the baseband processor, the RFIC and the antenna board including die analyses, processes and board cross-sections.
SP18394	2018/4 85	Texas Instruments AWR1642	77 & 79 GHz RFCMOS Radar Chipset	Single-chip radar (76 - 81 GHz) in an SoC device featuring MCU and DSP
RF FILTER				
SP17327	2017/5 122	Taiyo Yuden	SAW and BAW Band 7 Duplexer	Taiyo Yuden's Well-Proven Metal Seal Packaging and SAW/BAW technology in LTE Band 7 high isolation duplexer used in Skyworks' PAMiD
SP16283	2016/8 93	Murata FAJ15	SAW filter	The Samsung Galaxy S7 smartphone is the latest one to integrate Murata's front-end module with the FAJ15, featuring Murata's thermo-compensated technology

RF

Ref.	Date Pages	Manufacturer Product	Type of Product	Overview
OTHER				
SP17328	2017/12 300	Various RF IPD	RF Integrated Passive Devices	Description of each component, its major characteristics (substrate type (GaAs, silicon, glass), passivation layers, passive integration, etc.) and a comparison of all devices.
SP19400	2019/1 159 '7 & CAL77A2T4R FOM	Ainstein & Calterah	Ainstein K-77 Long Range Radar	BOM and the manufacturing cost of the radar sensor and review of the CAL77A2T4R transceiver, with a complete die analysis, cost analysis, and price estimate of the chips.

SOLID STATE LIGHTING

Ref.	Date Pages	Manufacturer Product	Type of Product	Overview
WHITE/BLUE LED				
SP17317	2017/3 70	Samsung LM101A	Chip Scale Package LED	The first Samsung Chip Scale Package LED is developed according to technical choices to reduce the manufacturing cost.
UV LED				
SP16273	2016/6 170	SETi UVTOP270TO39HS	UV LED	The UVTOP270TO39HS and SS35DF227513 are two 275nm UVC LEDs from Sensor Electronic Technology Inc. (SETi).
SP16272	2016/6 115	Crystal IS OPTAN280K-BL	UV LED	The OPTAN280K-BL and OPTAN-265N-SMD are two UVC LEDs, of 280nm and 265nm respectively, from Crystal IS.

SYSTEM

Ref.	Date Pages	Manufacturer Product	Type of Product	Overview
ENERGY				
SP17307	2017/1 81	Enphase S280	Solar microinverter	Best in class SmartGrid-ready 280VA inverter with new generation ASIC-based topology for lighter design and enhanced solar power management
CONSUMER				
SP17325	2017/3 132	Oculus Rift	Virtual Reality Head-Mounted Display	Detailed analysis of Oculus's HMD for VR experience
SP17280	2017/2 131	HTC Vive	VR Head-Mounted Display	HTC Vive Virtual Reality Head-Mounted Display
AUTOMOTIVE				
SP18432	2018/10 103	Aptiv SRR3	Aptiv's Third Generation of 77 GHz-Radar (SRR3)	Bill-of-material (BOM) and the manufacturing cost of the radar sensor, as well as a complete physical analysis of the MMIC
SP18401	2018/9 57	Ainstein T-79	Ainstein T-79: Automotive 79GHz Radar	Complete teardown analysis with the bill-of-material (BOM) and the manufacturing cost of the radar sensor
SP18386	2018/3 80	Continental SRR3-B	Continental SRR3-B Blind Spot Radar	Complete teardown analysis including BOM and manufacturing cost.
SP17357	2017/10 76	Continental SRL1	Short Range Lidar	Details on the full Continental SRL1 system's manufacturing and packaging processes, estimation of the manufacturing cost and selling price.
SP17354	2017/8 64	Bosch Ultrasonic sensor	Ultrasonic Sensor	Bill-of-material(BOM) and manufacturing cost physical analysis and manufacturing cost estimation of the Bosch transceiver IC.
SP17340	2017/6 35	LG LA080WV3 – 8-inch	Display with Touch Panel for Car Navigation	LG LA080WV3 – 8-inch Display with Touch Panel for Car Navigation
SP17329	2017/4 80	Continental MFC430	Forward Automotive Camera	Continental attempts to penetrate the forward camera market with a distinctive architecture and cost effective solution

SYSTEM

Ref.	Date Pages	Manufacturer Product	Type of Product	Overview
SP17324	2017/4 62	Bosch MPC2	Forward Automotive Camera	Bosch attempts to penetrate the forward camera market with a distinctive architecture and cost effective solution
SP17323	2017/4 77	TRW S-Cam3	Forward Automotive Camera	Third and latest version of TRW's best-selling S-Cam series forward camera
SP17321	2017/3 85	Continental ARS4A	77GHz Radar	Simultaneous long and short range 77GH7 radar
SP17320	2017/4 192	Leddartech LeddarVU	solid state high-definition LiDAR module	Without moving part, smallest form factor on the market and integrating the latest solid state technology, the LeddarVU8 is ready to compete with radars.
SP17313	2017/4 88	Bosch LRR4	77GHz Long Range Radar Sensor	The fourth generation of Bosch long range radar sensor set new boundaries for a more elegant, compactness and cost effectiveness module
SP17312	2017/1 80	Autoliv MRR	77GHz Multi Mode Radar	A compact, cost-effective (combining Long and Middle Range detection) and high-performance driving assistance system
SP16287	2016/9 135	Toyota Prius 4	Power control Unit	The Prius 4 module integrates Toyota's latest power card packaging, with double side cooling.

TEARDOWN

Ref.	Date Pages	Manufacturer Product	Type of Product	Overview
SP18437	2018/11 60	Xiaomi Mi 8 Explorer	Xiaomi Mi8 Explorer Teardown	Teardown photos, detailed package identification and descriptions.
SP18435	2018/10 60	Oppo Oppo Find X	Oppo Find X Teardown	Teardown photos, detailed package identifications and descriptions. Excel file summarizing the Oppo Find-X chipset and the distributions.
SP18412	2018/5 50	Huawei P20Pro	Huawei P20 Pro	Teardown photos,detailed package identifications and descriptions. Excel file summarizing the P20 Pro chipset and breaking down the devices by supplier,packages.
SP18409	2018/5 50	Apple iPhone X	Apple iPhone X	Teardown photos,detailed package identifications and descriptions. Excel file summarizing the Iphone X chipset and breaking down the devices by supplier,packages.
SP18402	2018/3 50	Samsung Galaxy S9+	Galaxy S9+	Teardown photos,detailed package identifications and descriptions. Excel file summarizing the S9+ chipset and breaking down the devices by supplier,packages.
SP17369	2017/11 150	Various	Thermal Management in Smartphones	Multiple comparisons based on physical analyses of the latest flagship smartphones. Evolution of thermal management technology tracked by manufacturer.

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